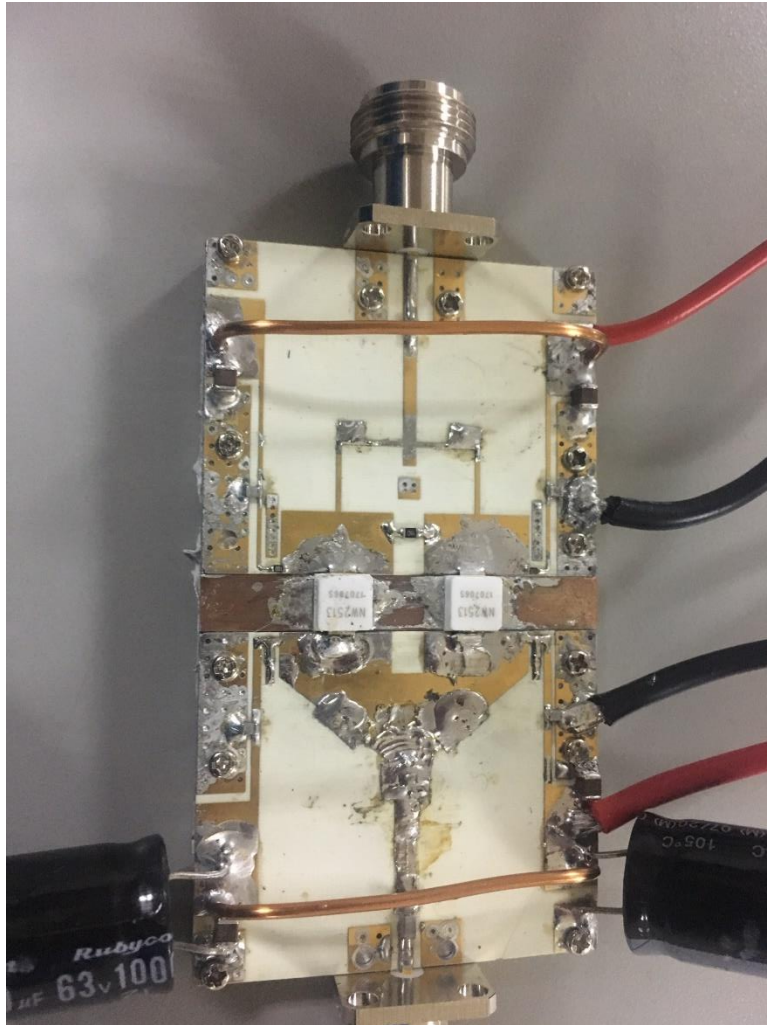


GPAV25250



1. Sizable heat plate
2. Thermally conductive material used
3. Bias sequencing
4. Class C operation
5. Load match (Attenuator S11 < -30dBc within 2.4-2.5G) and thermally stable
6. Short and thicker power supply wire suggested
7. Attention to the voltage drop due to high current, normally power supply reading isn't the real voltage fed into the device
8. Stated efficiency @ power on in first few seconds
9. Stabilized Efficiency might drop according to different cooling, we see 1% drop in our lab
10. 45V-55V -> 200W-300W
11. Engineering support

CW:
VGS = -3.3V

VDS(V)	Pout(dBm)	Pout(W)	Gain(dB)	EFF(%)@P3
48.3	54.08	260	14	71.0%

VDS = 50V VGS=-2.82V IDQ=150mA
CW / Pulse: pulse width 50us, duty cycle 10%

Freq(GHz)	P1(dBm)	P3(dBm)	P3(W)	EFF(%)@P3
2.40	54.16	55.07	321.45	72.90%
2.45	53.73	54.72	296.36	73.80%
2.50	53.14	54.24	265.48	72.91%

Thermal challenge pose difficulty to reach even better performance gotten by Pulse CW, we are working on this

